Nch 40V 10A Power MOSFET

V_{DSS}	40V
R _{DS(on)} (Max.)	14.3mΩ
I _D	±10A
P _D	2W

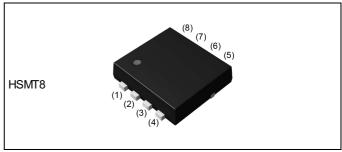
Features

- 1) Low on resistance.
- 2) High Power Package (HSMT8).
- 3) Pb-free lead plating; RoHS compliant.
- 4) Halogen Free.

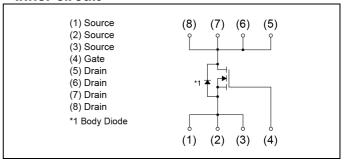
Application

Switching

Outline



Inner circuit



Packaging specifications

- : aonaging opcomeatione				
	Packing	Embossed Tape		
	Reel size (mm)	330		
Туре	Tape width (mm)	12		
	Basic ordering unit (pcs)	3000		
	Taping code	ТВ		
	Marking	G100GN		

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

	1	1	
Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	40	V
Continuous drain current	I _D	±10	Α
Pulsed drain current	I _{DP} *1	±40	Α
Gate - Source voltage	V_{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *2	10	Α
Avalanche energy, single pulse	E _{AS} *2	15.6	mJ
Power dissipation	P _D *3	2	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Doromotor	Cymah al	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R _{thJA} *3	-	62.5	-	°C/W

● Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 1mA$	40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	26.2	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V	1	-	1	μA	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1mA$	1.2	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.9	-	mV/°C	
Static drain - source	D *4	V _{GS} = 10V, I _D = 10A	-	11.0	14.3	C	
on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 10A	-	14.1	18.3	mΩ	
Gate resistance	R_G	f = , open drain	-	2.3	-	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 5V, I _D = 10A	7.5	-	-	S	

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} L $^{\simeq}$ 0.2mH, V_{DD} = 20V, R_{G} = 25 $\!\Omega$, STARTING T_{ch} = 25 $\!^{\circ}\!C$ Fig.3-1,3-2

^{*3} MOUNTED ON A CERAMIC BOARD

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			Linit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	615	-		
Output capacitance	C _{oss}	V _{DS} = 20V	-	100	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	28	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 20V, V_{GS} = 10V$	-	8.0	-		
Rise time	t _r *4	I _D = 5A	1	4.2	1	no	
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 4\Omega$	-	23.1	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	3.2	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymah al	Conditions		Values			1.1:4
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate above	O *4		V _{GS} = 10V	-	8.4	-	
Total gate charge	Qg*4	$V_{DD} \simeq 20V$		-	4.3	-	" C
Gate - Source charge	Q _{gs} *4	I _D = 10A	V _{GS} = 4.5V	-	1.6	-	nC
Gate - Drain charge	Q _{gd} *4			-	1.2	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	nbol Conditions –		Тур.	Max.	Offic
Continuous forward current	I _S	T _a = 25°C	-	-	1.67	Α
Pulse forward current	I _{SP} *1	1 _a - 25 C	-	-	40	Α
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 1.67A	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 10A, V _{GS} =0V	-	21	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	12	-	nC

Drain Current : I_D [A]

Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

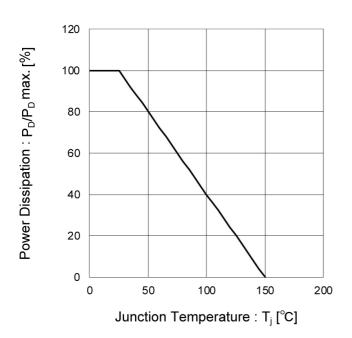
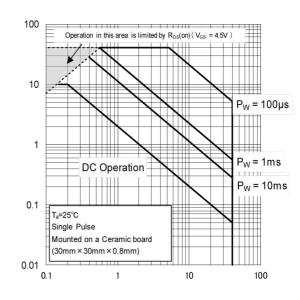


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage: V_{DS}[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

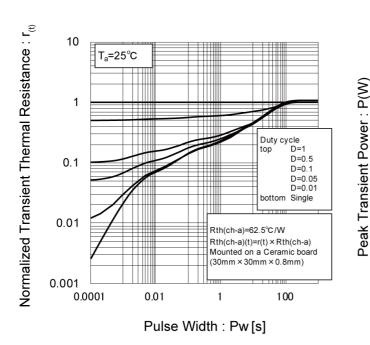
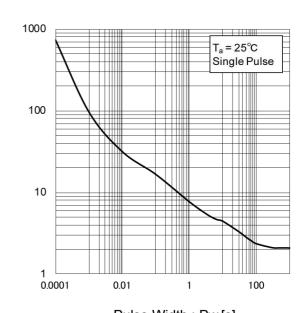


Fig.4 Single Pulse Maximum Power dissipation

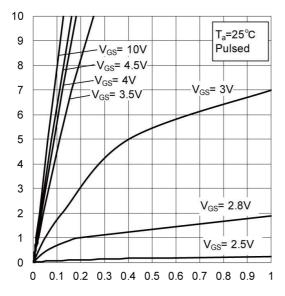


Pulse Width: Pw[s]

Drain Current : I_D [A]

• Electrical characteristic curves

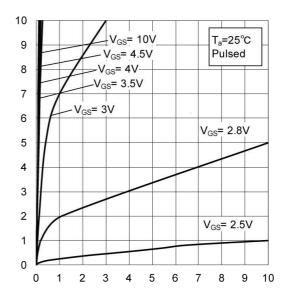
Fig.5 Typical Output Characteristics(I)



Drain Current : I_D [A]

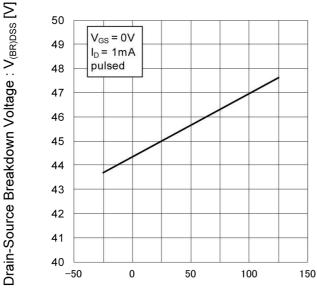
Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs. Junction Temperature



Junction Temperature : T_j [°C]

Gate Threshold Voltage : V_{GS(th)} [V]

6/11

• Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

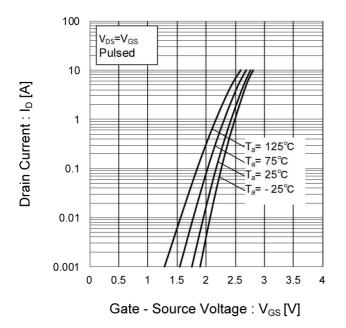
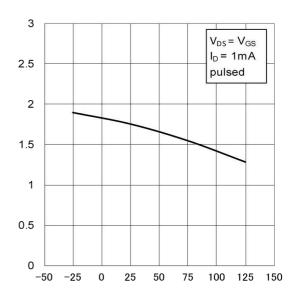
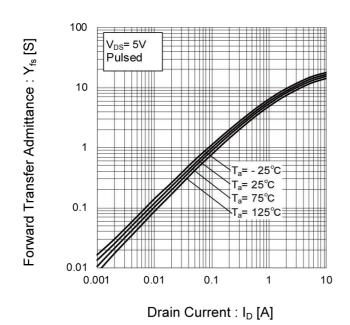


Fig.9 Gate Threshold Voltage vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.10 Transconductance vs. Drain Current



• Electrical characteristic curves

Fig.11 Drain Current Derating Curve

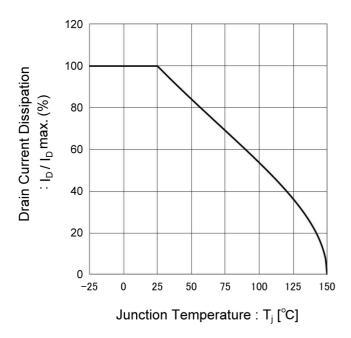
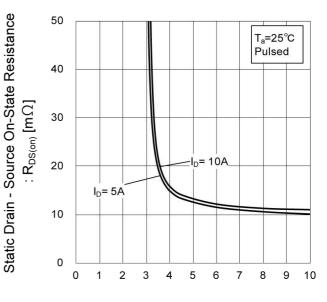
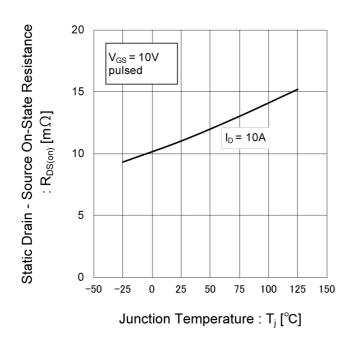


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Gate - Source Voltage : V_{GS} [V]

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



• Electrical characteristic curves

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

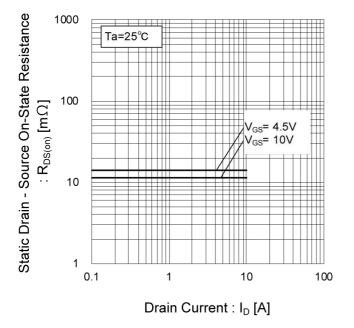


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

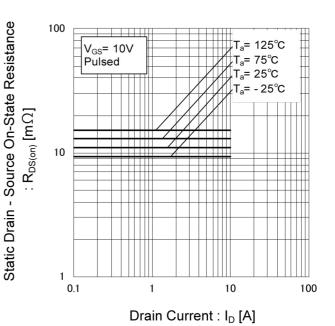
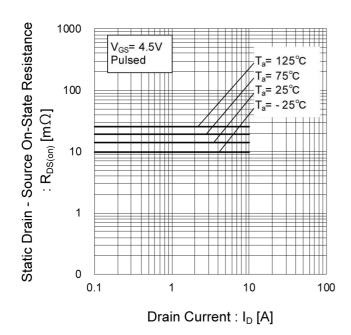


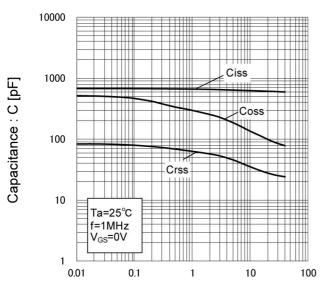
Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)





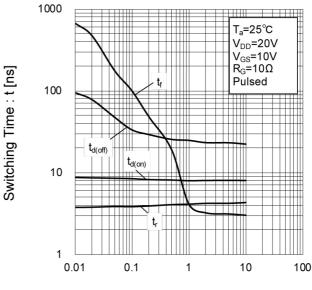
• Electrical characteristic curves

Fig.17 Typical Capacitance vs. Drain - Source Voltage



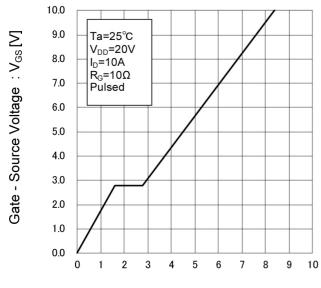
Drain - Source Voltage: V_{DS} [V]

Fig.18 Switching Characteristics



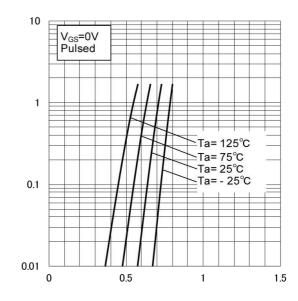
Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Qg [nC]

Fig.20 Source Current vs. Source Drain Voltage



Source-Drain Voltage: V_{SD}[V]

Source Current : Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

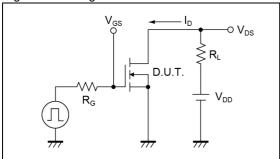


Fig.2-1 Gate Charge Measurement Circuit

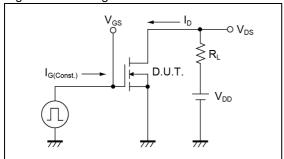


Fig.3-1 Avalanche Measurement Circuit

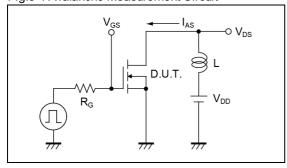


Fig.1-2 Switching Waveforms

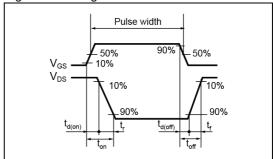


Fig.2-2 Gate Charge Waveform

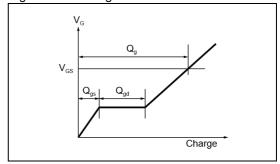
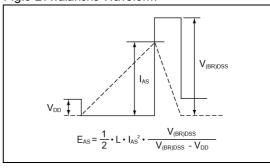


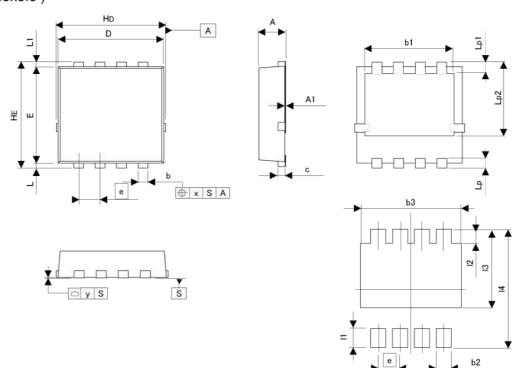
Fig.3-2 Avalanche Waveform



Dimensions

HSMT8

(3.3x3.3)



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	0.70	0.90	0.028	0.035
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
b1	2.50	2.70	0.098	0.106
С	0.10	0.30	0.004	0.012
D	3.10	3.30	0.122	0.130
E	2.90	3.10	0.114	0.122
е	0.	65	0.0	26
HD	3.20	3.40	0.126	0.134
HE	3.20	3.40	0.126	0.134
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.20	0.40	0.008	0.016
Lp1	0.25	0.45	0.010	0.018
Lp2	2.20	2.40	0.087	0.094
х	-	0.10		0.004
у	1961	0.10	-	0.004

DIM	MILIME	MILIMETERS		HES
DIIVI	MIN	MAX	MIN	MAX
b2	(E)	0.47		0.019
b3	6.70	2.70		0.106
11	100	0.50	- 4	0.020
12	70	0.55	2	0.022
13	3. 9	2.40		0.094
14	1 <u>2</u> 1	3.40	~ · · · · · · · · · · · · · · · · · · ·	0.134

Dimension in mm/inches



Notice

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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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